

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10568147
<b>Filing Date:</b>	13-Feb-2006
<b>Title of Invention:</b>	Abrasive compounds for semiconductor planarization
<b>First Named Inventor/Applicant Name:</b>	Kanshi Chinone
<b>Filer:</b>	LEE C WRIGHT/Akemi Ferebee
<b>Attorney Docket Number:</b>	062110

Filed as Large Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110